

ABSTRACT

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APPARATUS AND METHOD OF PLACING
SOLDER BALLS ONTO A SUBSTRATE

The invention provides an apparatus and method for positioning solder balls in a desired array on a substrate. A positioning means is provided for positioning the solder balls in positions corresponding to the array of positions the solder balls are to take up on the substrate. A container for receiving a plurality of solder balls and which is movable between a first position remote from the positioning means and a second position directly thereover supplies solder balls to the positioning means. Means are provided to bias the solder balls in the direction of movement of the container from the first to the second position whereby to reduce or obviate damage to the solder balls during such movement.

(Fig 2a)

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